FUTure PRopulsion and INTegration towards a hybrid-electric 50-seat regional aircraft Thermal Management challenges for HEA FUTPRINT50 aircraft class

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FUTPRINT 50 Consortium







FUTPRINT50 aircraft class: regional up to 50 pax

Milestone 1
Co-Ceede Aircraft Requirements Defined
Co-Ceede Aircraft Requirements
Co-Ceede Ai

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KEY ITEMS EIS 2035/2040 Up to 50 PAX

Design range: 400Km Max. range: 800Km Cruise speed: 450-550Km/h Take-off length: 1000m Max. alt: 25 000 feet FUTPRINT

-65 % perceived noise vs. 2000

-75% CO2 / (PAX x Km) vs. 2000

-90% NOx / (PAX x Km) vs. 2000

A/C taxi : emission free (electric) Design & Manufacture 4 Recycling





Thermal Management System

"Thermal Management is the ability to manage heat transfer between heat sources and sinks to control the temperature of aircraft subsystems/components in order to achieve comfort, safety and efficiency."



NASA







HEA Thermal Management Challenges

- High heat loads (transients and continuous);
- High power density (electronics miniaturization, *transmission*);
- High condensed electronics compartments;
- May need non-conventional solutions to the aircraft industry (risks on integration and safety aspects);
- TM system should minimize aircraft impacts: drag, power and weight;
- UK-UK (unknowns unknowns): unknown emergent behaviors due to integration







FUTPRINT50 TMS results

Advance the state of the art of HEA TMS:

- Updated TMS state of the art for HEA;
- Thermal management architectures for HEA:
 - Improve trade-offs at design stage;
 - New and improved models for simulation;
 - Models Integration (i.e., aircraft performance, propulsion, thermal management, etc.);

Roadmap for HEA TMS;

- Technologies demonstrators
- Regulation development support





Architectures and systems for HEA TMS





Overview of technologies for heat transfer

LIQUID COOLING SYSTEMS

The warm fluid passes through a heat exchanger to be cooled using the ambient as heat sink





PASSIVE SYSTEMS (E.G., HEAT PIPES, THERMOSYPHONS, VAPOR CHAMBERS)

The heat transfer is performed by the evaporation and condensation of the working fluid



THERMAL ACCUMULATORS (E.G., PHASE CHANGE MATERIALS)

The material reaches its specific phase change temperature



PUMPED TWO PHASE SYSTEMS (E.G., VAPOR CYCLE SYSTEMS, EVAPORATIVE COOLING)

Vapor cycle systems circulate refrigerant fluid via tubing, which absorbs and removes heat from a device and rejects to a heat sink





Overview of technologies for heat transfer

AIR COOLING (E.G., FANS, AIR CYCLE MACHINES, RAM AIR) Air cooling is accomplished by flowing air around/inside the heat loads



SKIN HEAT EXCHANGERS (E.G., FUSELAGE HEAT EXCHANGERS)

The aircraft skin act as a heat exchanger transferring heat to the ambient air



SEEBECK EFFECT AND PELTIER EFFECT

The build up of an electric potential across a temperature gradient and The energy transfer when an electric current passes through the junction of two dissimilar conductors



ABSORPTION REFRIGERATOR

Refrigerant is cooled during its absorption by the absorbent



Overview of technologies for heat transfer highlight | Crio



Exploiting synergies: challenges as opportunities (architectures)



- Explore opportunities in waste heat recovery and energy harvest;
- Perform a more integrated design (aeronautics, propulsion, electric systems, batteries, thermal management systems);
- Perform a mission optimized system design;
- Explore exergy as a figure of merit at aircraft and systems levels.





Key message

Integrated design is even more pressing for future HEA







THANK YOU!

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